

U1BC44, U1GC44, U1JC44

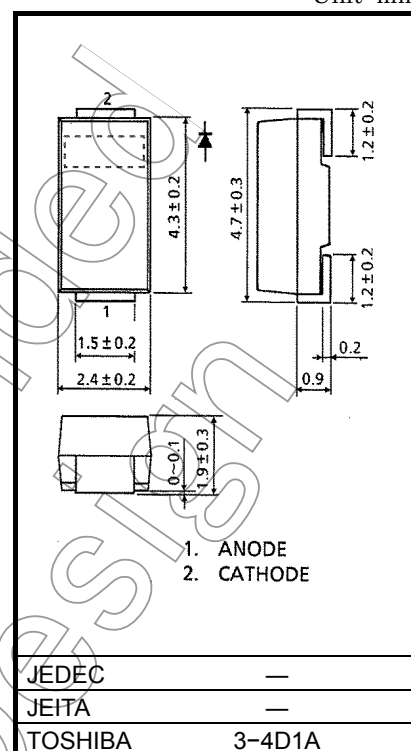
Unit: mm

FOR HYBRID USE

- Average Forward Current : $I_F (AV) = 1.0 \text{ A}$
- Repetitive Peak Reverse Voltage : $V_{RRM} = 100 \text{ V}, 400 \text{ V}, 600 \text{ V}$
- Mini Plastic Mold Package

ABSOLUTE MAXIMUM RATINGS ($T_a = 25^\circ\text{C}$)

CHARACTERISTIC		SYMBOL	RATING	UNIT
Repetitive Peak Reverse Voltage	U1BC44	V_{RRM}	100	V
	U1GC44		400	
	U1JC44		600	
Average Forward Current	On Ceramic Substrate	I_F (AV)	1.0 ($T_a = 75^{\circ}\text{C}$)	A
	On Glass-epoxy Substrate		0.9 ($T_a = 25^{\circ}\text{C}$)	
Peak One Cycle Surge Forward Current (Non-Repetitive)		I_{FSM}	30 (50Hz)	A
			33 (60Hz)	
Junction Temperature		T_j	-40~150	$^{\circ}\text{C}$
Storage Temperature Range		T_{std}	-40~150	$^{\circ}\text{C}$



Weight: 0.06g

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

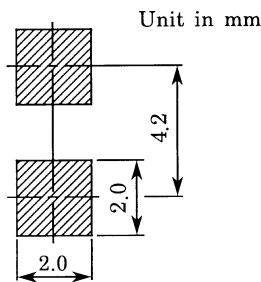
ELECTRICAL CHARACTERISTICS ($T_a = 25^\circ\text{C}$)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN	TYP.	MAX	UNIT
Peak Forward Voltage	V_{FM}	$I_{FM} = 1.0 \text{ A}$	—	—	1.2	V
Repetitive Peak Reverse Current	I_{RRM}	$V_{RRM} = \text{Rated}$	—	—	10	μA
Thermal Resistance	$R_{th(j-a)}$	DC On ceramic substrate	—	—	60	$^\circ\text{C} / \text{W}$
		On glass-epoxy substrate	—	—	120	

MARKING

Abbreviation Code	Part No.
BC	U1BC44
GC	U1GC44
JC	U1JC44

STANDARD SOLDERING PAD



Handling Precaution

The absolute maximum ratings denote the absolute maximum ratings, which are rated values and must not be exceeded during operation, even for an instant. The following are the general derating methods that we recommend when you design a circuit with a device.

VRRM: We recommend that the worst case voltage, including surge voltage, be no greater than 80% of the absolute maximum rating of VRRM for a DC circuit and be no greater than 50% of that of VRRM for an AC circuit. VRRM has a temperature coefficient of 0.1%/°C. Take this temperature coefficient into account designing a device at low temperature.

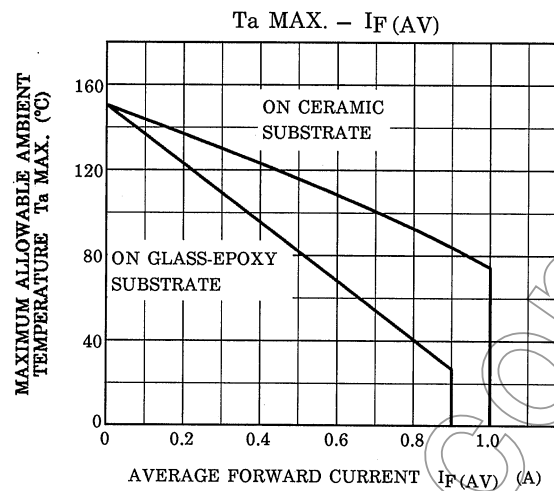
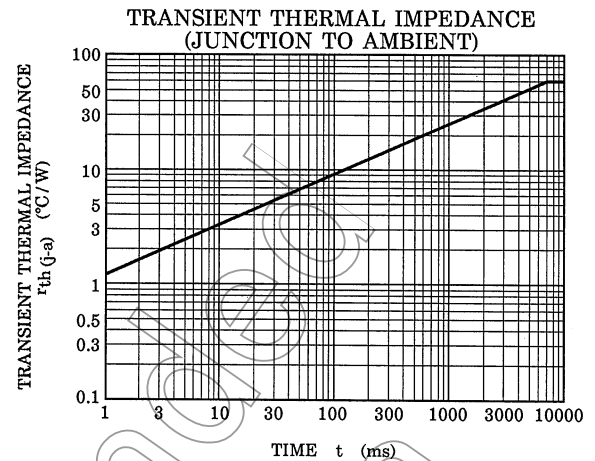
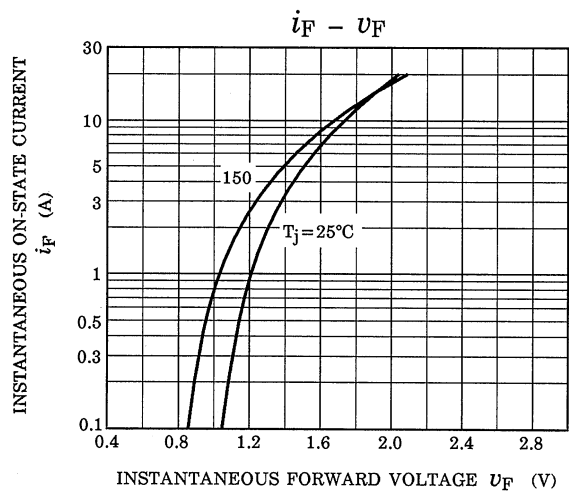
IF(AV): We recommend that the worst case current be no greater than 80% of the absolute maximum rating of IF(AV). Carry out adequate heat design. If you can't design a circuit with excellent heat radiation, set the margin by using an allowable Tamax-IF(AV) curve.

This rating specifies the non-repetitive peak current in one cycle of a 50-Hz sine wave, condition angle 180. Therefore, this is only applied for an abnormal operation, which seldom occurs during the lifespan of the device.

We recommend that a device be used at a Tj of below 120°C under the worst load and heat radiation conditions.

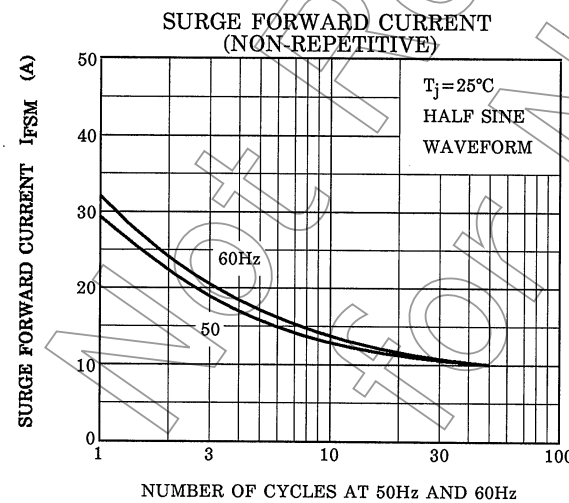
Thermal resistance between junction and ambient fluctuates depending on the device's mounting condition. When using a device, design a circuit board and a soldering land size to match the appropriate thermal resistance value.

Please refer to the Rectifiers databook for further information.



	ON CERAMIC SUBSTRATE	ON GLASS-EPOXY SUBSTRATE
Soldering land : a □	2mm □	6mm □
Substrate size : b □	50mm □	50mm □
Substrate thickness : c □	0.64t	1.6t

Diagram showing package dimensions: a (soldering land), b (substrate size), and c (substrate thickness).



RESTRICTIONS ON PRODUCT USE

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